

VISIONARY COMPUTING



CUG **2018** STOCKHOLM

AMD 

**AMD UPDATE
CUG 2018**



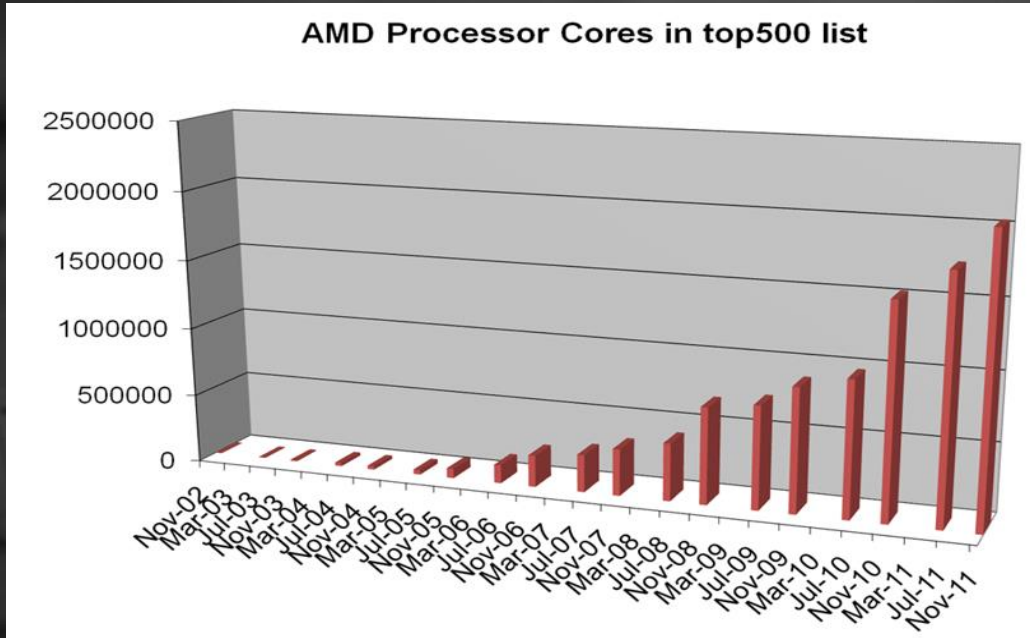
CRAY[®]
THE SUPERCOMPUTER COMPANY

CRAY AND AMD PAST SUCCESS IN HPC

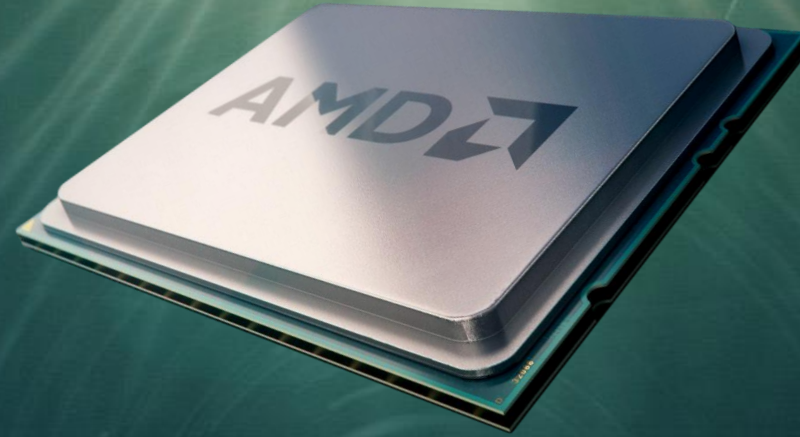
AMD IN TOP500 LIST 2002 TO 2011



2011 - AMD IN FASTEST MACHINES IN 11 COUNTRIES



Rank	Country	Site	Partner
3	United States of America	Oak Ridge	Cray
12	Germany	Universitaet Stuttgart	Cray
19	United Kingdom (Scotland)	Edinburgh	Cray
31	Korea (South)	KMA	Cray
34	Switzerland	CSCS	Cray
41	Canada	Sherbrooke	SGI
44	Sweden	KTH	Cray
50	Brazil	INPE	Cray
61	Taiwan	Taiwan HPC Center	Acer
78	Austria	Vienna Scientific Center	<u>Megware</u>
203	Finland	CSC	Cray



“ZEN” A FRESH APPROACH

Designed from the Ground up for Optimal Balance of Performance and Power

Totally new
high-performance
core design

New high-bandwidth,
low latency
cache system

Simultaneous
multithreading (SMT)
for high throughput

Energy-efficient FinFET
design tuned for enterprise
applications

8 ZEN CORES PER DIE

Compute

8 Zen x86 cores

4MB total L2 cache

16MB total L3 cache

Memory

2 channels ddr4 with ECC

2 DIMM per channel

up to 256GB per channel

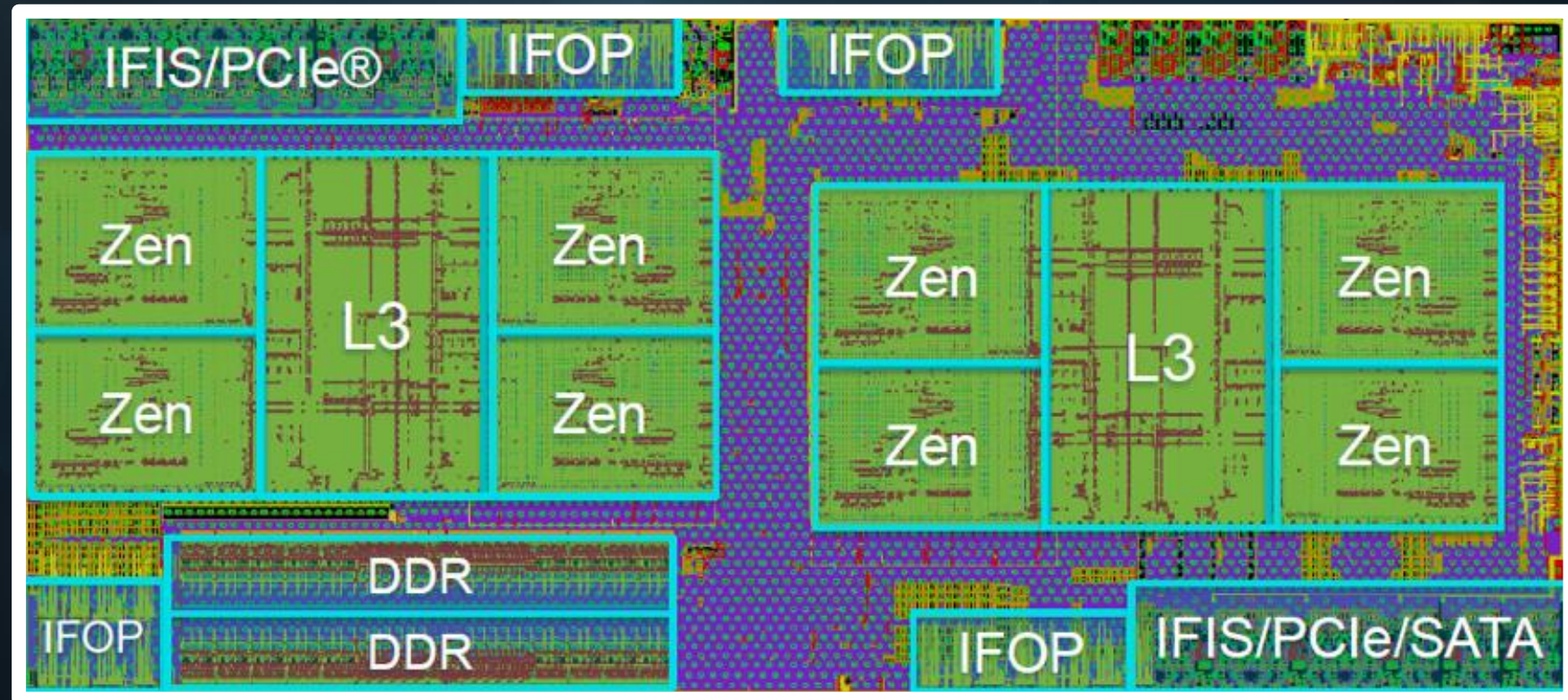
Infinity fabric

Connects die and I/O

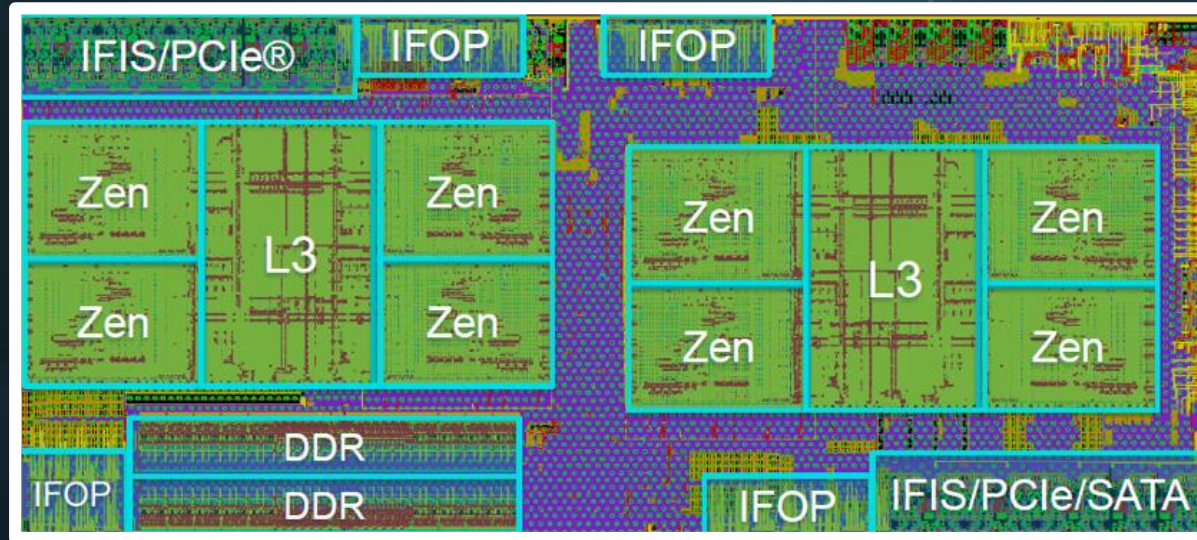
Security

On die security processor

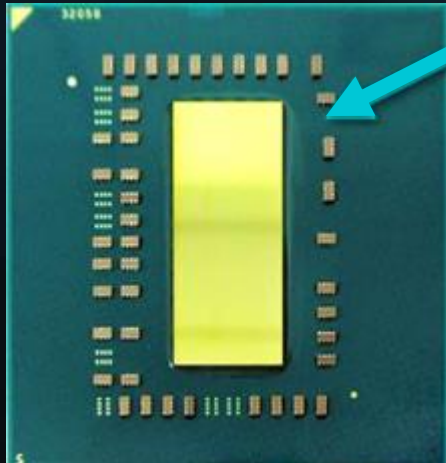
Memory encryption per VM



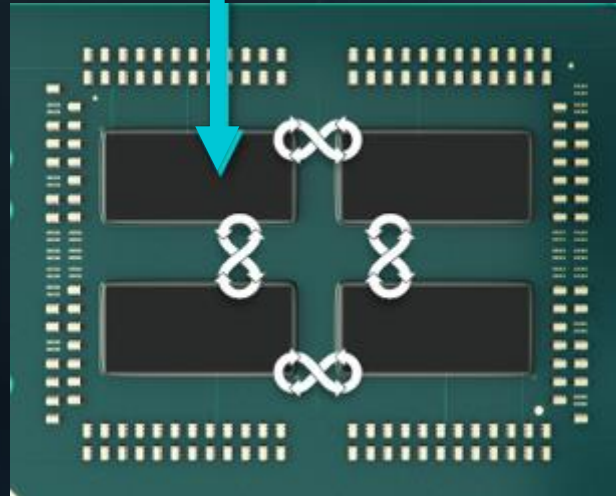
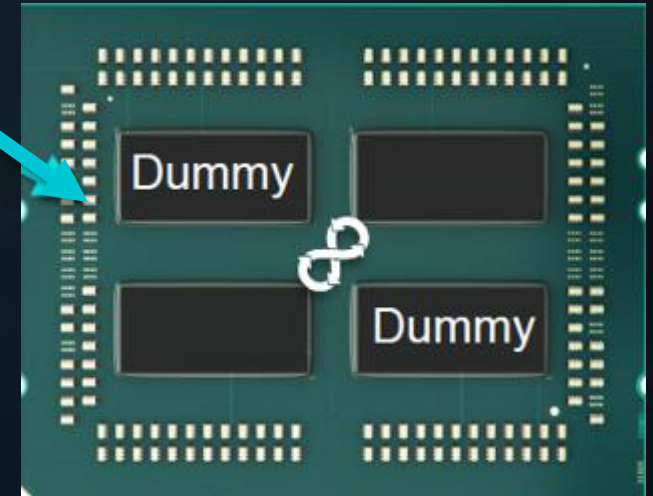
ZEN IN MULTI-CHIP ARCHITECTURES



Ryzen 8c Desktop



Threadripper
16c Workstation



EPYC 32c HPC server

POWER AND PERFORMANCE



RYZEN 2 – 12NM – IMPROVES TOP BOOST CLOCK



Scan for more info

AMD Ryzen™ 7 2700X

8 Core, 16 Thread Processor

4.3 GHz Max Boost, 3.7 GHz Base

EPYC 7000 AT A GLANCE

Lowering TCO through an Optimal Balance of Compute, Memory, I/O and Security

COMPUTE

8 to 32 AMD “Zen” x86 cores
(16 to 64 threads)

512KB L2 cache per core
(16 MB total L2 cache)

64MB shared L3 cache
(8MB per 4 cores)

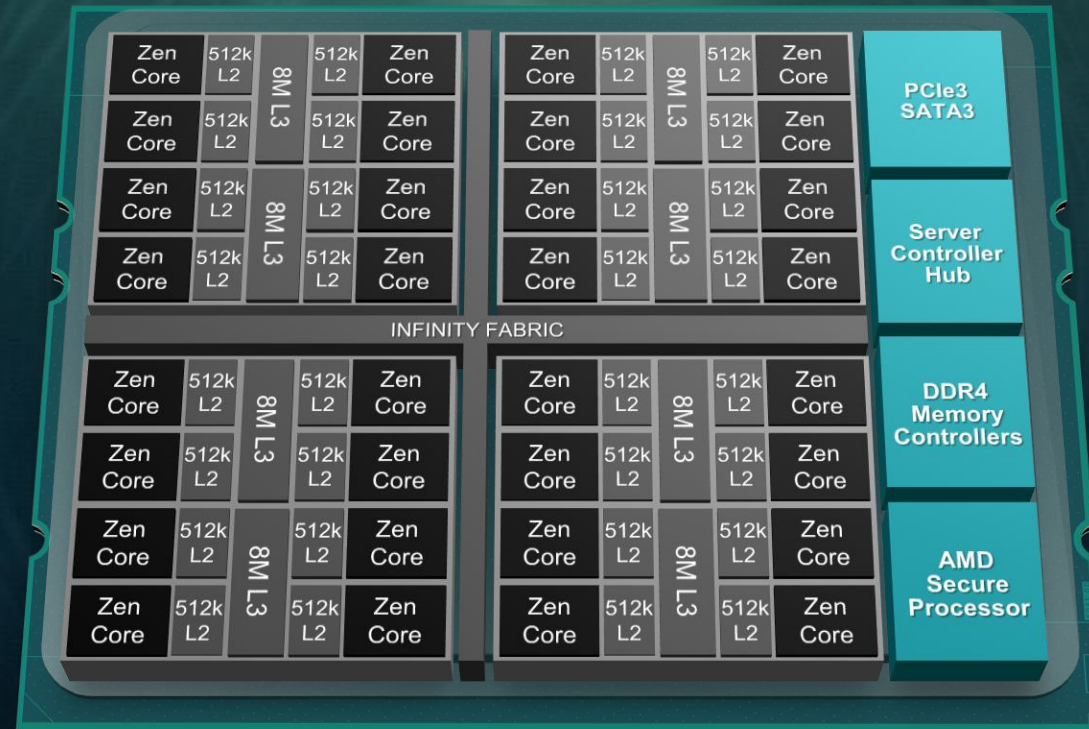
TDP range: 120W-180W

MEMORY

8 channel DDR4 with ECC
up to 2666 MHz

RDIMM, LRDIMM, 3DS,
NVDIMM

2 DIMMs/channel capacity
of 2TB/socket



INTEGRATED I/O

– NO CHIPSET

128 lanes PCIe Gen3

- Used for PCIe, SATA, and Coherent Interconnect
- Up to 32 SATA or NVMe devices

Server Controller Hub
(USB, UART, SPI, LPC, I2C, etc.)

SECURITY

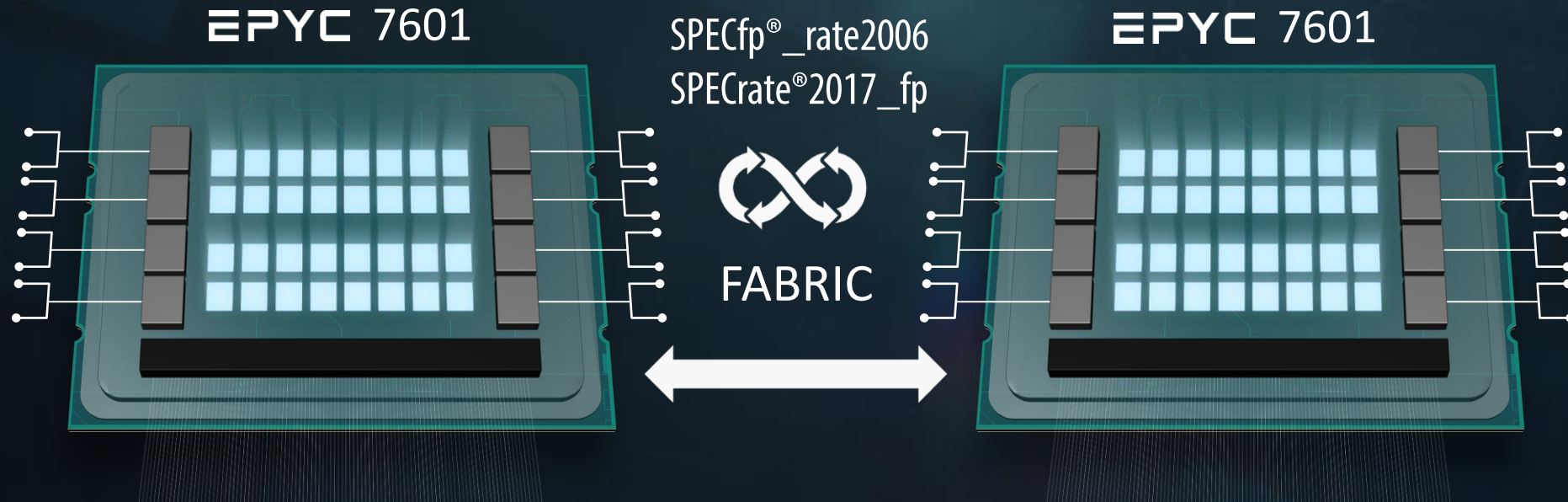
- Dedicated Security Subsystem
- Hardware Root-of-Trust
- Hardware Memory Encryption

FEATURE CONSISTENCY AND SIMPLIFIED PRODUCT STACK



	EPYC 32 CORE		EPYC 24 CORE		EPYC 16 CORE		EPYC 8 CORE	
	Model	Price	Model	Price	Model	Price	Model	Price
ONE-SOCKET AND TWO-SOCKET	7601	\$4,200	7451	\$2,400	7351	\$1,100	7251	\$475
	7551	\$3,400	7401	\$1,850	7301	\$825		
	7501	\$3,400			7281	\$650		
ONE-SOCKET ONLY	7551P	\$2,100	7401P	\$1,075	7351P	\$750		
DDR4-2666	✓		✓		✓		DDR4-2400	
2TB memory capacity	✓		✓		✓		✓	
128 lanes PCIe3®	✓		✓		✓		✓	
Turbo boost	✓		✓		✓		✓	
SMT	✓		✓		✓		✓	

WORLD RECORD BENCHMARKS!



14% More Cores ¹

33% More Memory Bandwidth ²
2.6x More Memory Capacity ³

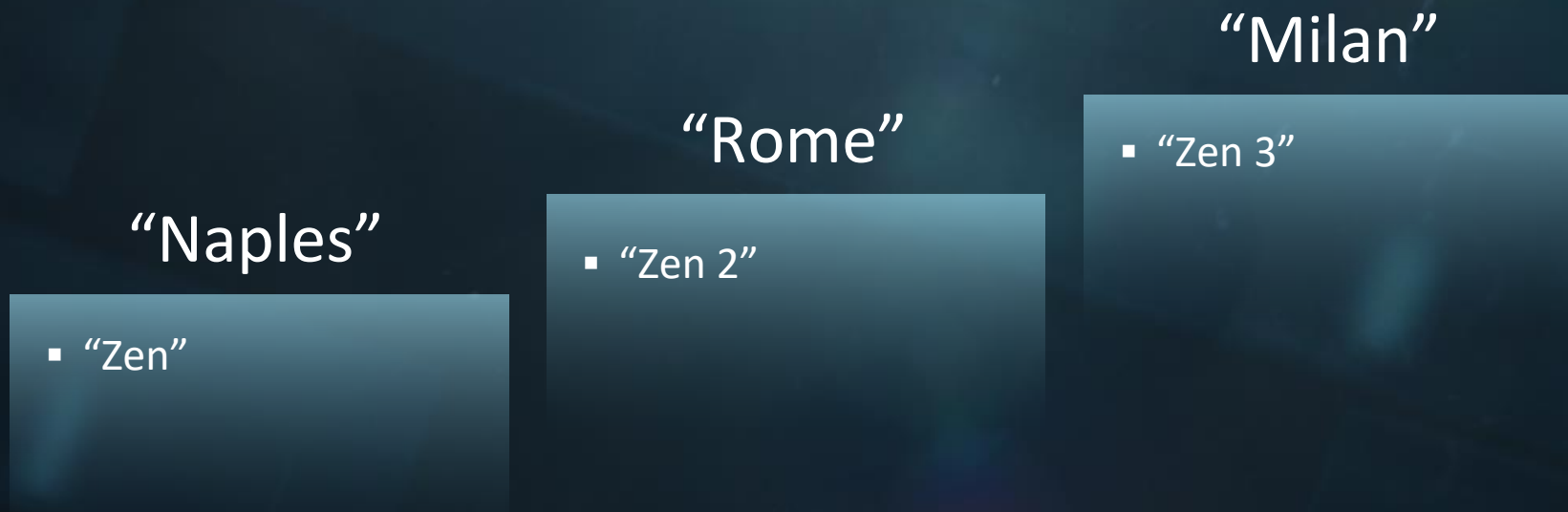
UP TO 2.6x More Performance / \$ ⁴

Feature and perf/\$ comparison to 2 Intel Xeon Platinum 8180.
Perf/\$ based on published prices and published SPECfp_rate2016 scores on spec.org
World record benchmarks based on SPECfp®_rate2006 and SPECrate®2017_fp scores on spec.org as of Jan. 18, 2018
See Endnotes

SPEC CPU2006 FP RATE BASE

PERFORMANCE VS CPU \$ PRICE

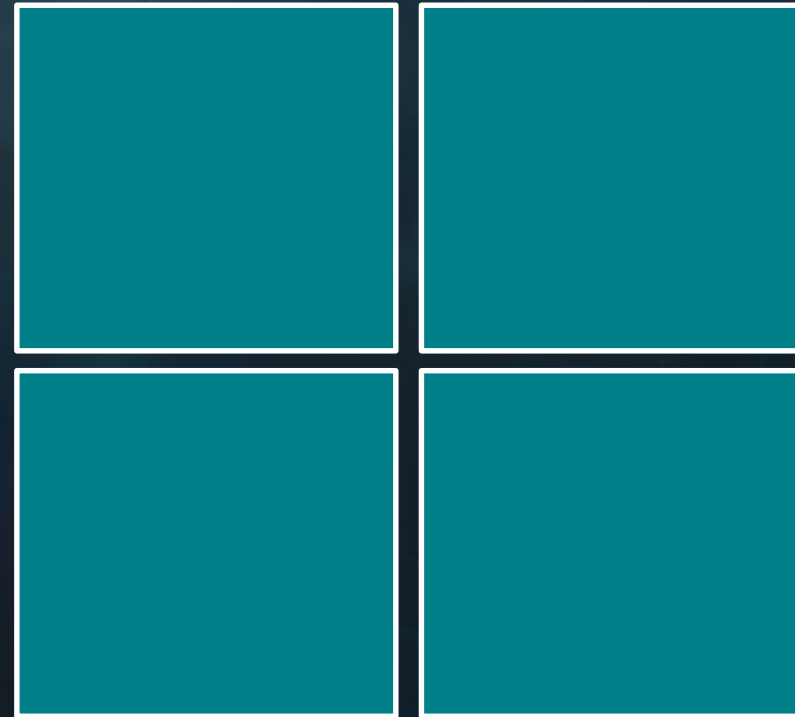




AMD IS BACK TO STAY

“NAPLES” TO “ROME” - WILL BE EPYC TOO

Artistic impression of 14nm to 7nm process shrink



The image features the AMD logo in a bold, white, sans-serif font, centered horizontally. The logo consists of the letters 'A', 'M', 'D', and a stylized square symbol with a diagonal cut. The background is a dark, grayscale photograph of a laptop keyboard, with the keys and the 'STEELSeries' branding on a key visible. The lighting is dramatic, with the logo standing out sharply against the dark, textured background.

AMD

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